



100% Material Declaration Data Sheet FF1152

PK137 (v1.2) September 28, 2006

Material Declaration Data Sheet

Average Weight: 14.0 g

Component	Substance Description	CAS# or Description	% of Component	Use in Product	Component Weight/ Substance Weight (in grams)	Component % of Total
Silicon Die					0.8848	6.32%
	Silicon	7440-21-3	100.00		0.8848	
Solder Bump					0.0154	0.11%
	Tin	7440-31-5	63.00		0.009702	
	Lead	7439-92-1	37.00		0.005698	
Underfill					0.112	0.80%
	Silica	60676-86-0	70.00		0.0784	
	Epoxy Resin A	9003-36-5	20.00		0.0224	
	Epoxy Resin B	25068-38-6	3.00		0.00336	
	Hardener	19900-65-3	7.00		0.00784	
Heat Sink					8.3258	59.47%
	Copper	7440-50-8	99.97		8.32330226	
	Chromium	7440-22-4	0.03		0.00249774	
Heat Sink Adhesive					0.0007	0.05%
	Organopolysiloxane mixture	N/A	100.00		0.0007	
Substrate					3.7156	26.54%
	Copper	7440-50-8	47.61	Metal Layer	1.76899716	
	Nickel	7440-02-0	0.51	Metal Layer	0.01894956	
	Gold	7440-57-5	0.11	Metal Layer	0.00408716	
	Glass Fiber	N/A	10.35		0.3845646	
	BT (core)	N/A	27.54		1.02327624	
	Halogen fire retardant	N/A	5.25		0.195069	
	Solder Mask	N/A	8.63		0.32065628	
Solder Balls					0.9394	6.71%
	Tin	7440-31-5	63.00		0.591822	
	Lead	7439-92-1	37.00		0.347578	

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Revision History

The following table shows the revision history for this document.

Date	Revision	Revision
3/23/06	1.0	Initial release.
7/13/06	1.1	100% Material Declaration.
9/28/06	1.2	Updated component descriptions.